

CLAIMS

1. A method for plating on at least one  
conductive pattern on a surface of a substrate, said  
substrate having at least a first surface and a second  
5 surface, said method comprising the steps of:

placing the substrate on an electrode being  
part of a plating holder such that said second surface of  
said substrate is in contact with said electrode and said  
conductive pattern is temporarily electrically connected to  
10 said electrode; and

applying a plating solution on said first  
surface of said substrate thereby inhibiting exposure of  
said second surface to said plating solution.

characterised in that said electrode and said  
15 conductive pattern are temporarily electrically connected  
by forming a polysilicon or an amorphous silicon conductor  
to temporarily connect said conductive pattern with a  
contact to the substrate, said contact being formed on the  
first surface of the substrate, and by providing an  
20 electrical connection between said contact and said  
electrode.

2. A method as recited in claim 1, wherein  
said conductive pattern is positioned on a first die and  
said contact is positioned on a second die different from  
25 said first die.

3. A method as recited in claim 2, wherein  
after said conductive pattern is plated, said method  
further comprises the step of dicing the substrate

4. A method as in claim 1, wherein prior to  
30 applying the plating solution, a resist layer is deposited  
on said conductive pattern and patterned in order to create  
at least one covered area and at least one uncovered area,  
said uncovered area being exposable to said plating  
solution.

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5. A method as recited in claim 1, where said plating solution comprises an element selected from a group comprising Ag, Cu, Au, Pt, Ti, Ni and Co.

6. A substrate having at least a first surface and a second surface opposite to said first surface, said first surface being exposable to a plating solution, said substrate comprising

a conductive pattern being positioned at said first surface of a substrate;

a contact to the first surface of the substrate; and

said conductive pattern being temporarily electrically connected by a polysilicon or an amorphous silicon conductor with said contact and said contact being electrically connected with said second surface.

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